Hysol

ECCOBOND G909

August 2010

PRODUCT DESCRIPTION

ECCOBOND G909 provides the following product characteristics:

Technology	Epoxy
Appearance	Grey
Cure	Heat cure
Product Benefits	• One component • High strength • Non-sag • Thixotropic • Excellent peel strength • High tensile shear strength over a broad temperature range
Application	Assembly
Surfaces	Copper, Aluminum, Fiberglass reinforced plastics and Oily steel
Operating Temperature	-40 to 150 °C

ECCOBOND G909 is designed for very high strength structural bonding especially for dissimilar substrates that will be exposed to a wide range of operating temperatures.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Specific Gravity	1.15
Press Flow, seconds	65
Sag Resistance, mm	12.7
Shelf Life @ 4°C, months	3
Flash Point - See MSDS	

TYPICAL CURING PERFORMANCE

Cure Schedule

90 minutes @ 100°C or
30 minutes @ 120°C or
20 minutes @ 150°C

Post Cure

2 to 4 hours at the highest expected use temperature

Cure schedules are "the time at cure temperature to achieve full product cure". The times does not include the time required to ramp-up to cure temperature.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

Hardness Shore D:	
@ 25ºC	78
@ 120ºC	35

TYPICAL PERFORMANCE OF CURED MATERIAL

Tensile Lap Shear Strength :

Aluminium @ 25°C	N/mm²	40
	(psi)	(5,800)
Aluminum @ 100°C	N/mm²	20.3
	(psi)	(2,950)
Steel @ 25°C	N/mm²	32.4
	(psi)	(4,700)

"T" Peel Strength, ISO 11339:

Aluminum	N/mm	5.25
	(lb/in)	(30)

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

DIRECTIONS FOR USE

1. Complete cleaning of the substrates should be performed to remove contamination such as oxide layers, dust, moisture, salt and oils which can cause poor adhesion or corrosion in a bonded part.
2. Apply adhesive to all surfaces to be bonded and join together.
3. In most applications only contact pressure is required.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 4°C. Storage greater than or below 4°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
N x 0.225 = lb
N/mm x 5.71 = lb/in
N/mm² x 145 = psi
MPa x 145 = psi
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·mm x 0.142 = oz·in
mPa·s = cP

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Note

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